

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|--|--|------------------|
| 1 | 2521 | measure\$ same first same workpiece | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2003/11/19 14:38 |
| 2 | 1685 | (measure\$ same first same workpiece) and method | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2003/11/19 14:39 |
| 3 | 1539 | ((measure\$ same first same workpiece) and method) and second | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2003/11/19 14:41 |
| 4 | 231 | ((measure\$ same first same workpiece) and method) and second) and semiconductor | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2003/11/19 16:14 |
| 5 | 1381 | measuring same thickness same layer same first | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2003/11/19 16:15 |
| 6 | 779 | measuring same thickness same layer same first same second | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2003/11/19 16:15 |
| 7 | 207 | (measuring same thickness same layer same first same second) and operating | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2003/11/19 16:19 |
| 8 | 4 | ((measuring same thickness same layer same first same second) and operating) and recipe | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2003/11/19 16:15 |
| 9 | 5 | ("5590051" "5637351" "5724144" "6060370" "6306669").PN. | USPAT | 2003/11/19 16:17 |
| 10 | 64 | ((measuring same thickness same layer same first same second) and operating) and semiconductor | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2003/11/19 16:20 |
| 11 | 181 | ((measuring same thickness same layer same first same second) and operating) and method | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2003/11/19 16:20 |